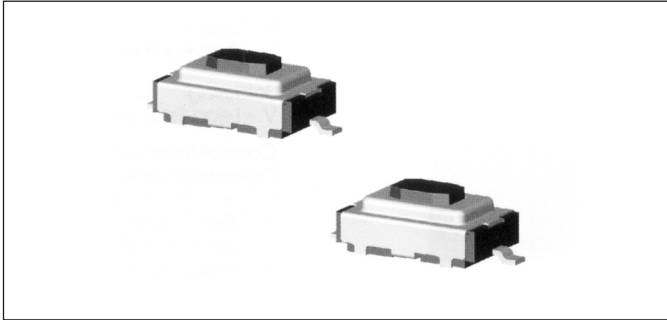
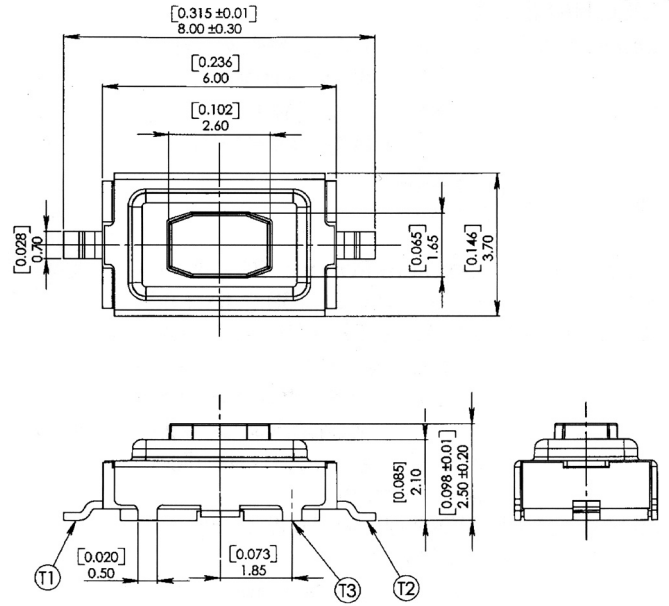


TMG-3 SERIES
(Thinner Type)



DIMENSIONS



FEATURES

1. Sharp click feel with a positive tactile feedback.
2. Ultraminiature structure suitable for high density mounting.
Economic but high reliability.
3. Insert molding in the contact with special treatment prevents flux build-up during soldering and permits auto-dipping.

MATERIALS

- △ Cover: Nickel Silver.
- △ Contact Disc: Stainless with silver cladding.
- △ Terminal: Brass with silver plated.
- △ Base: UL94V-O Nylon High-Temp. Thermoplastic.
Color: Black.
- △ STEM: UL94V-O Nylon High-Temp. Thermoplastic.
Color: Brown.
- △ Tape: Teflon.

General Tolerance: ± 0.2 mm (± 0.008 ")



SPECIFICATION

Mechanical

- Operation Force: 160 ± 50gf Brown (N)
- Stroke: 0.25 + 0.1mm - 0.1mm.
- Operation Temperature Range: -25 °C to 70 °C
- Storage Temperature Range: -30 °C to 80 °C
- Vibration Test: MIL-STD-202F METHOD 201A.
Frequency: 10-55-10Hz/1 minute.
Directions: X, Y, Z, three mutually perpendicular directions.
Time: 2 hours each direction.
High reliability.
- Shock Test: MIL-STD-202F METHOD 213 B.
CONDITION A.
Gravity: 50G (peak value), 11 msec.
Direction and times: 6 sides and 3 times in each direction.
High reliability.

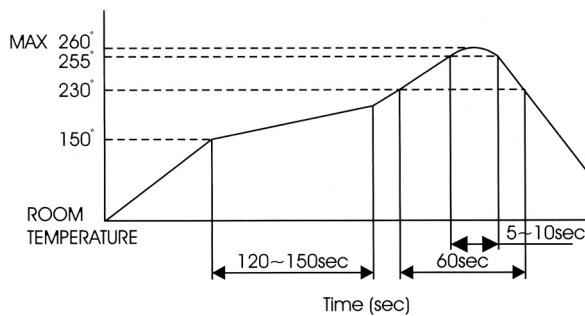
Electrical

- Electrical Life: 50,000 cycles for 160gf.
- Rating: 50 mA, 12VDC.
- Contact Resistance: 100 mΩ max.
- Insulation Resistance: 100 MΩ min. at 500VDC.
- Dielectric Strength: 250VAC/1 minute.
- Contact Arrangement: 1 pole 1 throw.

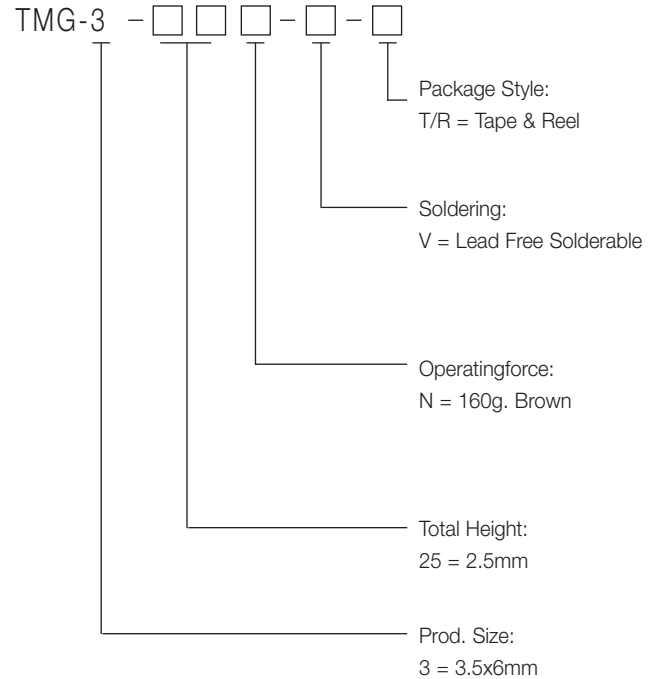
SOLDERING PROCESSES

- △ Hand soldering: Use a soldering iron of 30 watts, controlled at 320 °C approximately 2 seconds while applying solder.
- △ Reflow Soldering: When applying reflow soldering, the peak temperature or the reflow oven should be set to 260 °C max.

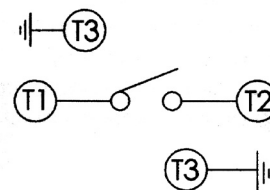
Temperature Profile:



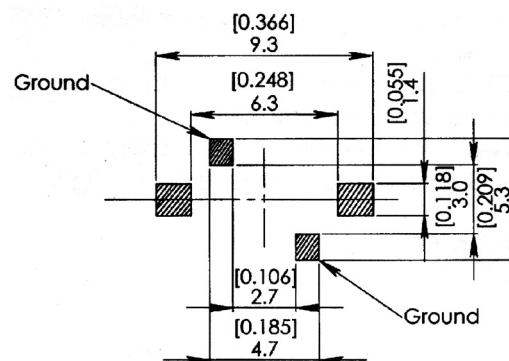
HOW TO ORDER



CIRCUIT



P.C.B. LAYOUT



PACKAGING

Tape and Reel: 2800 pcs/reel